# SDIA5012 TYPE

### **FEATURE**

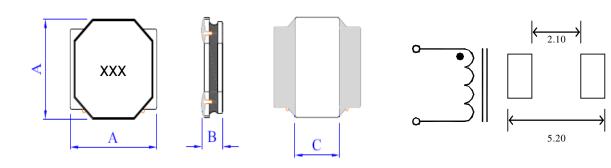
1. Low profile and small size (Height: 2.00mm Max)

## Applications

- 1. LCD panels
- 2. Digital camera, PDA and others

### Shape and Dimension





A=5.00±0.20m/m; B=1.20 m/m Max; C= 2.00m/m REF

### Specification

| Part Number   | L(uH) | STAMP | DCR(ΩMax) | Isat(A) | Irms |
|---------------|-------|-------|-----------|---------|------|
| SDIA5012-1R0N | 1.0   | 1R0   | 0.084     | 3.7     | 2.20 |
| SDIA5012-2R2M | 2.2   | 2R2   | 0.102     | 2.5     | 2.00 |
| SDIA5012-3R3M | 3.3   | 3R3   | 0.192     | 2.0     | 1.45 |
| SDIA5012-4R7M | 4.7   | 4R7   | 0.276     | 1.7     | 1.25 |
| SDIA5012-6R8M | 6.8   | 6R8   | 0.360     | 1.2     | 1.10 |
| SDIA5012-100M | 10    | 100   | 0.516     | 1.1     | 0.90 |
| SDIA5012-150M | 15    | 150   | 0.744     | 0.9     | 0.75 |

Note1. Measurement frequency of Inductance value: at 100KHz, 0.25V

Note3. Inductance Tolerance: N: ±30%; M: ±20%

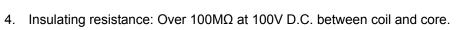
Note4. Isat :  $\triangle L/L \le 30\%$  (This indicates the value of current when the inductances is 30% lower than its initial value at D.C. superimposition)

Note5.Packaging: Taping; Quantity: 1000 Pieces/reel

## GENERAL CHARACTERISTICS

- 1. Operating temperature range: -40 TO + 105°C (Includes temperature when the coil is heated)
- 2. External appearance: On visual inspection, the coil has no external defects.
- Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Ywithstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.



- 5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
- 6. Temperature characteristics: Inductance coefficient (0~2,000)x10-6/°C (-25~+80°C).
- 7. Humidity characteristics(Moisture Resistance): Inductance deviation within ±5%, after 96 hours in 90~95% relative humidity at 40 ±2°C and 1 hour drying under normal condition.
- 8. Vibration resistance: Inductance deviation within ±5%, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
- 9. Shock resistance: Inductance deviation within ±5%, after being dropped once with 981m/s2 (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
- 10. Resistance to Soldering Heat: 260°C, 10 seconds(See attached recommend reflow)
- 11. Storage environment: Storage condition: Temperature Range:  $10^{\circ}\text{C} \sim 35^{\circ}\text{C}$  (Generally:  $21^{\circ}\text{C} \sim 31^{\circ}\text{C}$ ) , Humidity Range:  $50\% \sim 80\%$  RH (Generally:  $65\% \sim 75\%$ ); Transportation condition: Temperature Range:  $-35^{\circ}\text{C} \sim 85^{\circ}\text{C}$ , Humidity Range:  $50\% \sim 95\%$  RH
- 12. Use components within 6 months. If 6 months or more have elapsed, check solderability before use.
- 13. Reflow profile recommend:

#### Lead-free heat endurance test

#### Lead-free the recommended reflow condition

